

OSRAM LT Q99G.01

Datasheet

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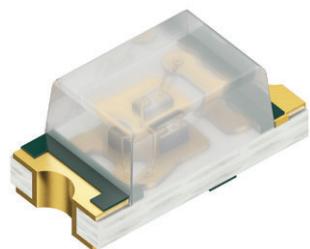
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am **OSRAM**

Chip LED 0603

LT Q99G.01

The Chip LED 0603 is the product of choice for low power status indication in electronics. The small package size allows compact designs, like 7-segment displays, symbol backlighting or button and switch illumination in control panels. The high brightness of the LED ensures good visibility at any time.



Applications

- Appliances & Tools
- Display Backlighting
- Factory Automation
- Home & Building Automation
- Projection & Display
- Static Signaling

Features

- Package: SMT package 0603, clear epoxy
- Chip technology: Volume emitter on Sapphire (AlInGaN)
- Typ. Radiation: 150°
- Color: $\lambda_{\text{dom}} = 528 \text{ nm}$ (● true green)
- Corrosion Robustness Class: 2B
- ESD: 1 kV acc. to ANSI/ESDA/JEDEC JS-001 (HBM)

Ordering Information

Type	Luminous Intensity ¹⁾ $I_F = 5 \text{ mA}$ I_v	Ordering Code
LT Q99G.01-R2T1-25-1	140 ... 355 mcd	Q65113A5257

Maximum Ratings

Parameter	Symbol	Values
Operating Temperature	T_{op}	min. -40 °C max. 85 °C
Storage Temperature	T_{stg}	min. -40 °C max. 85 °C
Junction Temperature	T_j	max. 95 °C
Forward current $T_s = 25 \text{ }^\circ\text{C}$	I_F	min. 1 mA max. 20 mA
Forward Current pulsed $t \leq 100 \mu\text{s}$; $D = 0.03$; $T_s = 25 \text{ }^\circ\text{C}$	$I_{F_{pulse}}$	max. 100 mA
Surge Current $t \leq 10 \mu\text{s}$; $D = 0.005$; $T_s = 25 \text{ }^\circ\text{C}$	I_{FS}	max. 100 mA
Reverse voltage ²⁾ $T_s = 25 \text{ }^\circ\text{C}$	V_R	max. 5 V
ESD withstand voltage acc. to ANSI/ESDA/JEDEC JS-001 (HBM)	V_{ESD}	1 kV

Characteristics

$I_F = 5 \text{ mA}$; $T_S = 25^\circ\text{C}$

Parameter	Symbol	Values	
Peak Wavelength	λ_{peak}	typ.	518 nm
Dominant Wavelength ³⁾	λ_{dom}	min.	520 nm
		typ.	528 nm
		max.	540 nm
Spectral Bandwidth at 50% $I_{\text{rel,max}}$	$\Delta\lambda$	typ.	34 nm
Viewing angle at 50% I_V	2ϕ	typ.	140 °
Forward Voltage ⁴⁾ $I_F = 5 \text{ mA}$	V_F	min.	2.60 V
		typ.	2.90 V
		max.	3.10 V
Reverse current ²⁾ $V_R = 5 \text{ V}$	I_R	typ.	0.01 μA
		max.	10 μA
Real thermal resistance junction/solderpoint ⁵⁾	$R_{\text{thJS real}}$	typ.	250 K / W
		max.	340 K / W

Brightness Groups

Group	Luminous Intensity ¹⁾ $I_F = 5 \text{ mA}$ min. I_v	Luminous Intensity ¹⁾ $I_F = 5 \text{ mA}$ max. I_v	Luminous Flux ⁶⁾ $I_F = 5 \text{ mA}$ typ. Φ_v
R2	140 mcd	180 mcd	670 mlm
S1	180 mcd	224 mcd	850 mlm
S2	224 mcd	280 mcd	1060 mlm
T1	280 mcd	355 mcd	1330 mlm

Forward Voltage Groups

Group	Forward Voltage ⁴⁾ $I_F = 5 \text{ mA}$ min. V_F	Forward Voltage ⁴⁾ $I_F = 5 \text{ mA}$ max. V_F
3X	2.60 V	2.70 V
3Y	2.70 V	2.80 V
3Z	2.80 V	2.90 V
4X	2.90 V	3.00 V
4Y	3.00 V	3.10 V

Wavelength Groups

Group	Dominant Wavelength ³⁾ min. λ_{dom}	Dominant Wavelength ³⁾ max. λ_{dom}
2	520 nm	525 nm
3	525 nm	530 nm
4	530 nm	535 nm
5	535 nm	540 nm

Group Name on Label

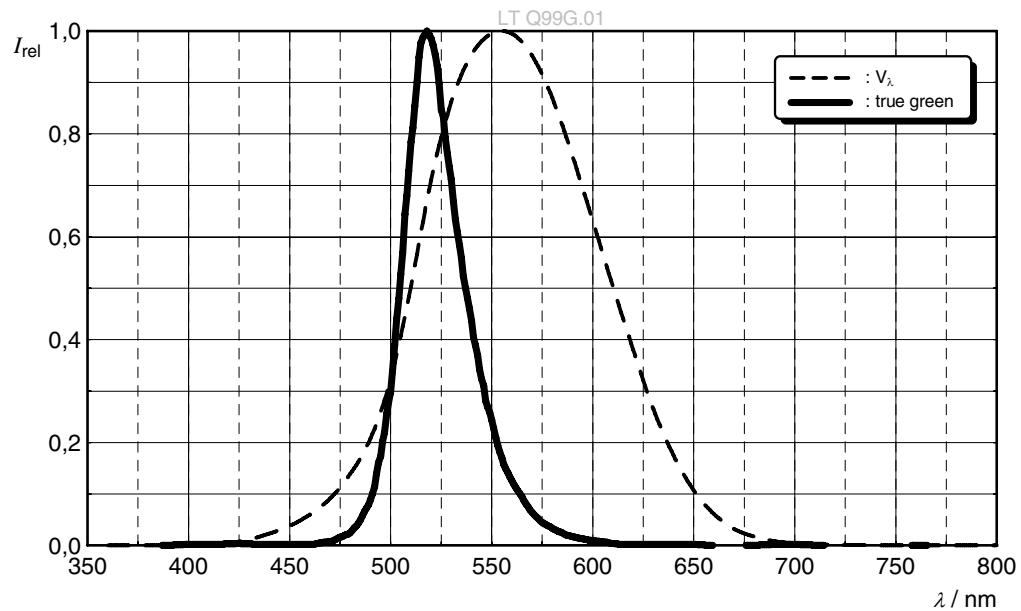
Example: R2-2-3X

Brightness	Wavelength	Forward Voltage
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R2	2	3X
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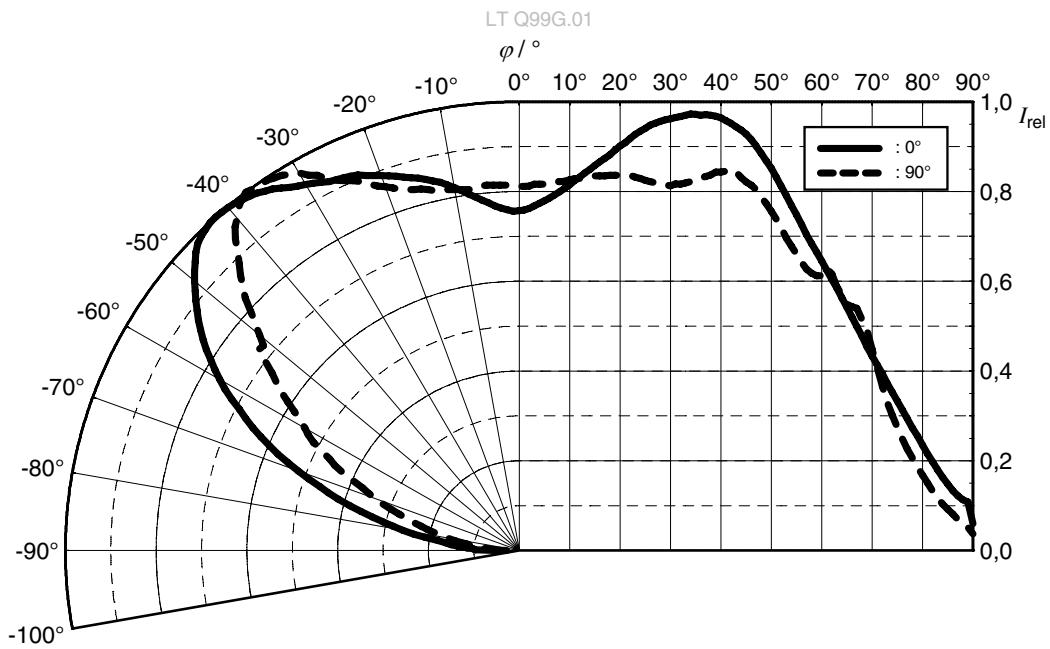
Relative Spectral Emission ⁶⁾

$I_{\text{rel}} = f(\lambda)$; $I_F = 5 \text{ mA}$; $T_S = 25 \text{ }^\circ\text{C}$



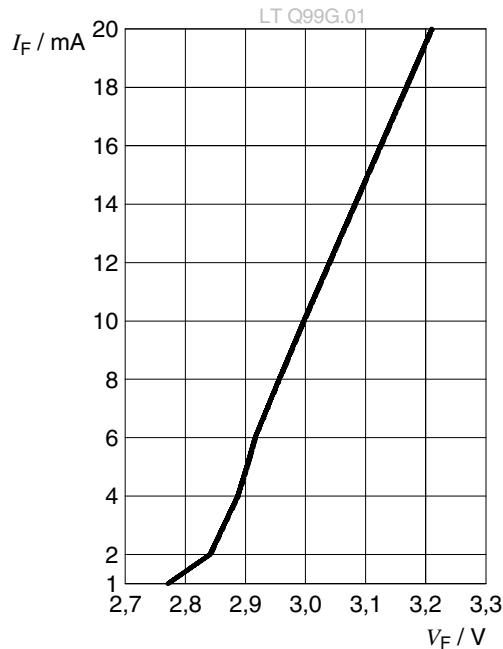
Radiation Characteristics ⁶⁾

$I_{\text{rel}} = f(\phi)$; $T_S = 25 \text{ }^\circ\text{C}$



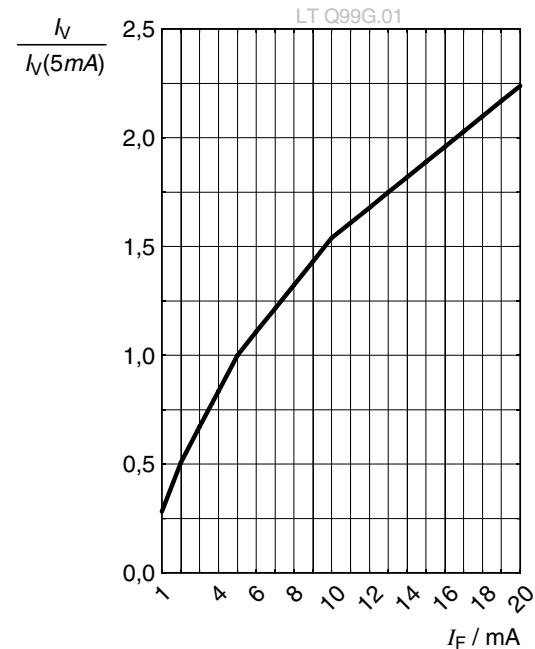
Forward current ⁶⁾

$I_F = f(V_F)$; $T_S = 25^\circ\text{C}$



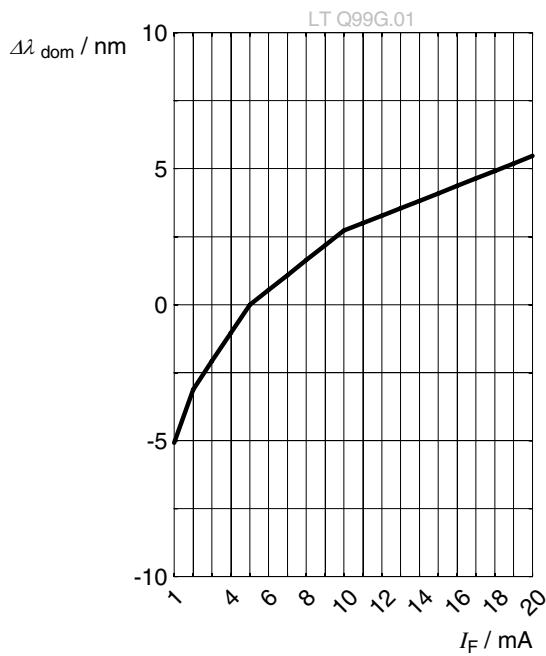
Relative Luminous Intensity ^{6), 7)}

$I_v/I_v(5 \text{ mA}) = f(I_F)$; $T_S = 25^\circ\text{C}$



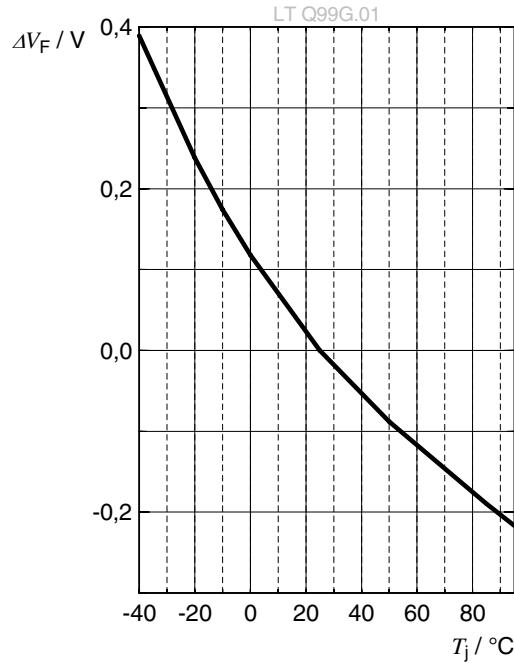
Dominant Wavelength ⁶⁾

$\Delta\lambda_{\text{dom}} = f(I_F)$; $T_S = 25^\circ\text{C}$



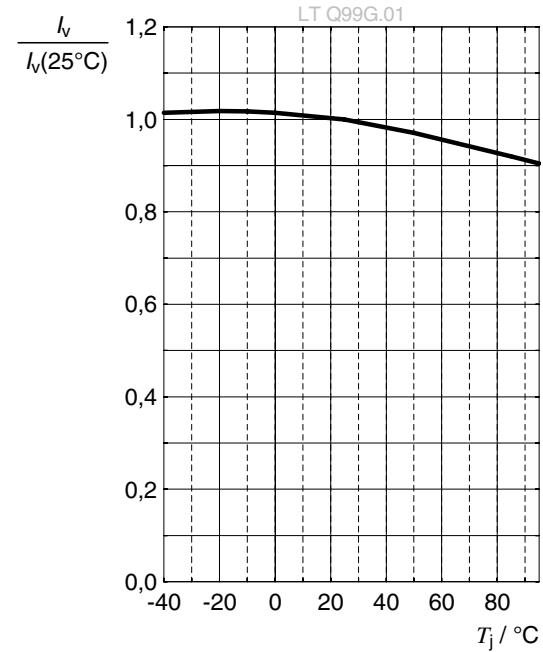
Forward Voltage ⁶⁾

$$\Delta V_F = V_F - V_F(25^\circ\text{C}) = f(T_j); I_F = 5 \text{ mA}$$



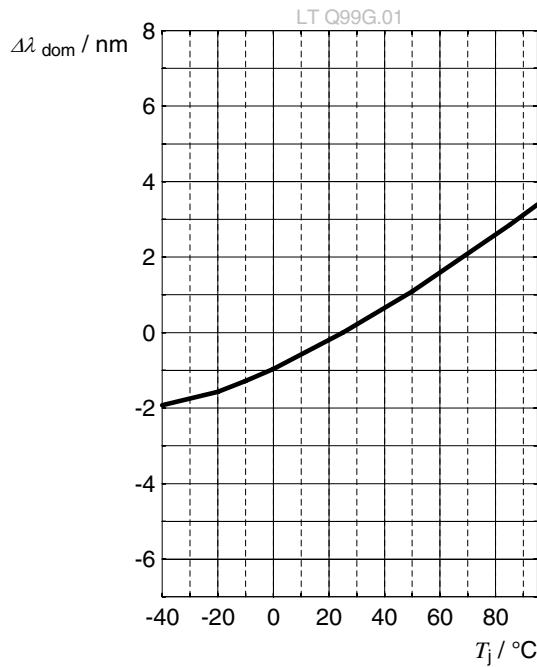
Relative Luminous Intensity ⁶⁾

$$\frac{I}{I_v}(25^\circ\text{C}) = f(T_j); I_F = 5 \text{ mA}$$



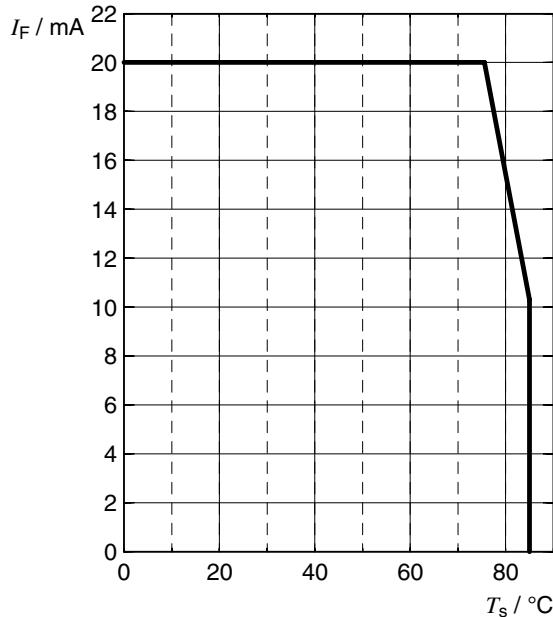
Dominant Wavelength ⁶⁾

$$\Delta \lambda_{\text{dom}} = \lambda_{\text{dom}} - \lambda_{\text{dom}}(25^\circ\text{C}) = f(T_j); I_F = 5 \text{ mA}$$



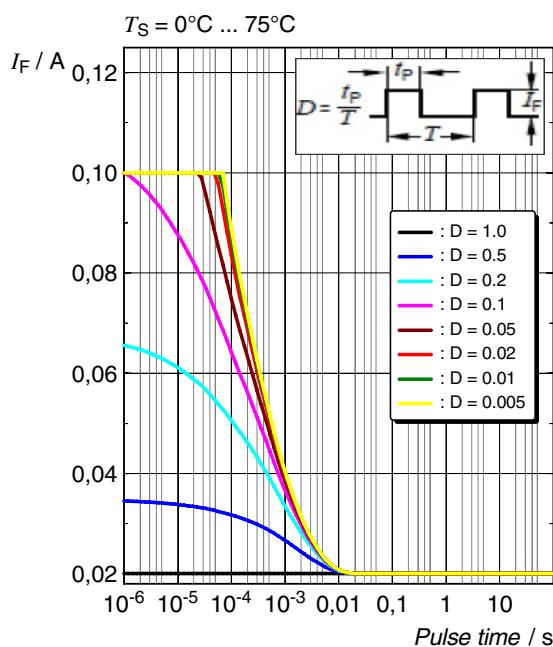
Max. Permissible Forward Current ⁵⁾

$$I_F = f(T)$$



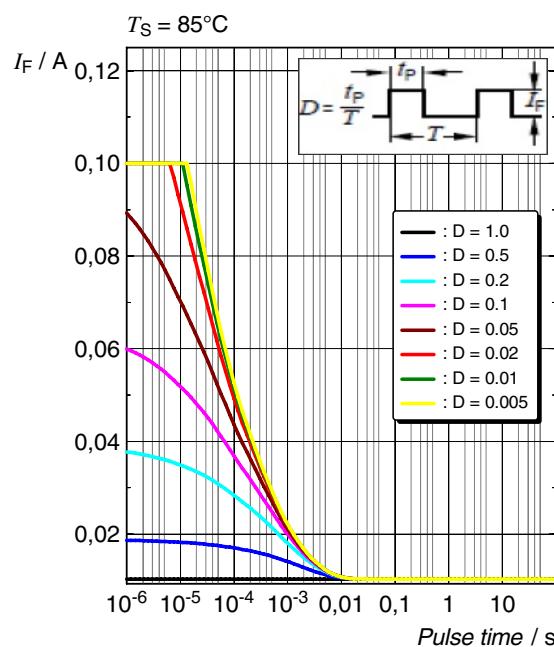
Permissible Pulse Handling Capability

$$I_F = f(t_p); D: \text{Duty cycle}; T_s = 25^\circ\text{C}$$

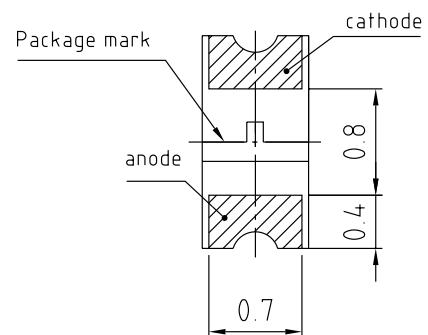
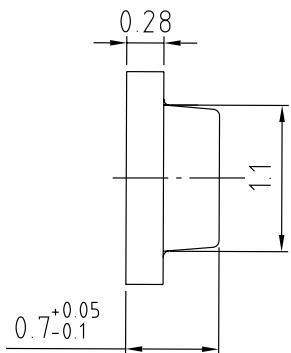
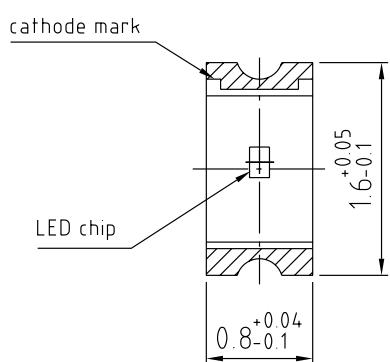


Permissible Pulse Handling Capability

$$I_F = f(t_p); D: \text{Duty cycle}; T_s = 85^\circ\text{C}$$



Dimensional Drawing ⁸⁾



general tolerance ± 0.1

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lead finish Ag 

Further Information:

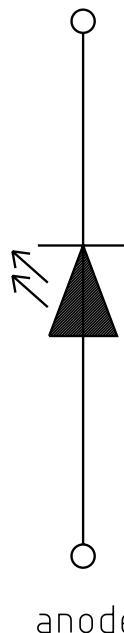
Approximate Weight: 1.4 mg

Corrosion test: Class: 2B

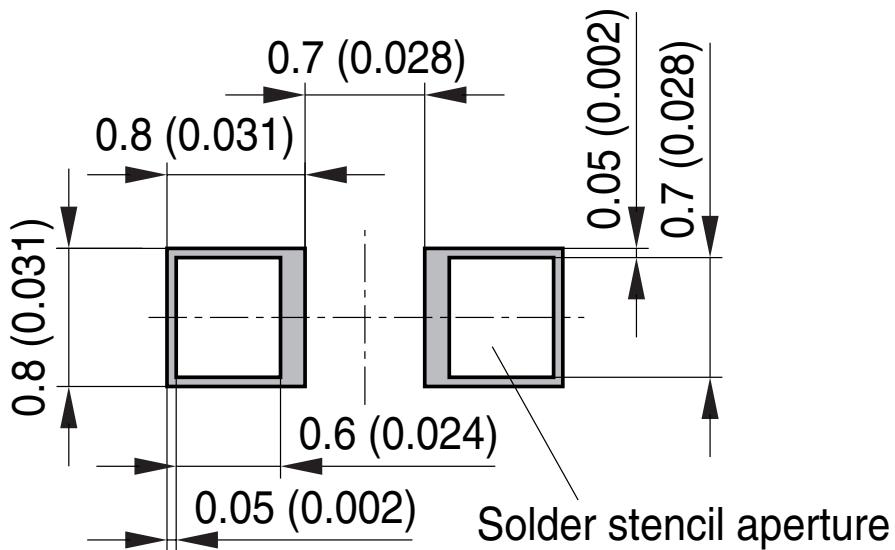
Test condition: 25°C / 75 % RH / 10 ppm H₂S / 21 days (IEC 60068-2-43)

Electrical Internal Circuit

cathode



Recommended Solder Pad ⁸⁾



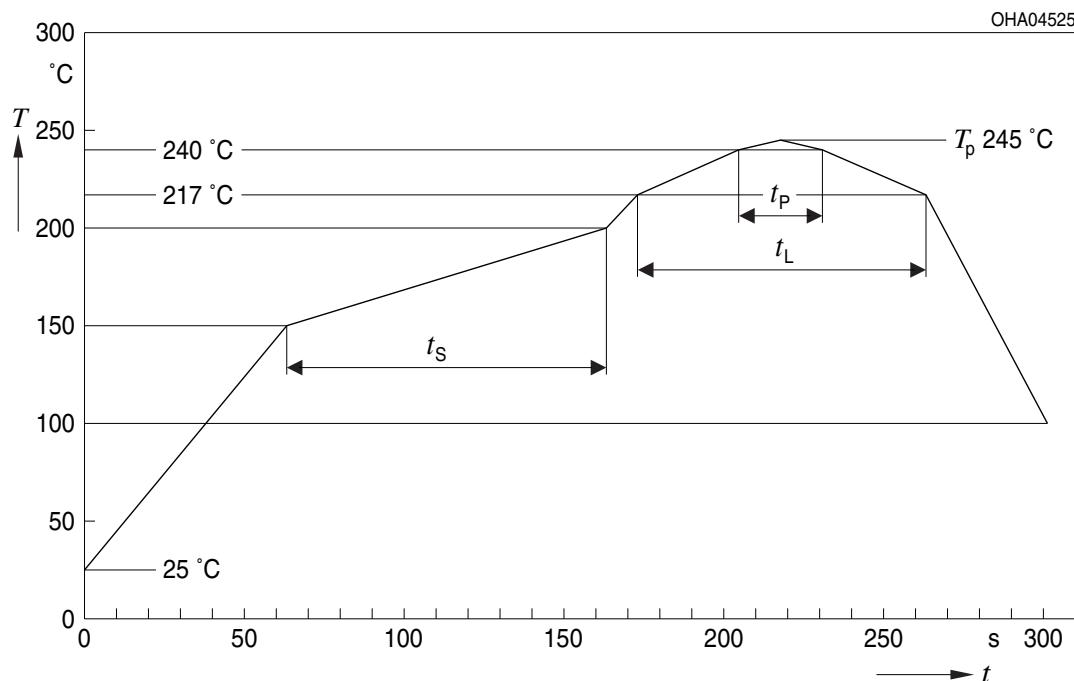
Copper solder pad

OHPY3832

For superior solder joint connectivity results we recommend soldering under standard nitrogen atmosphere. Package not suitable for ultra sonic cleaning.

Reflow Soldering Profile

Product complies to MSL Level 3 acc. to JEDEC J-STD-020E

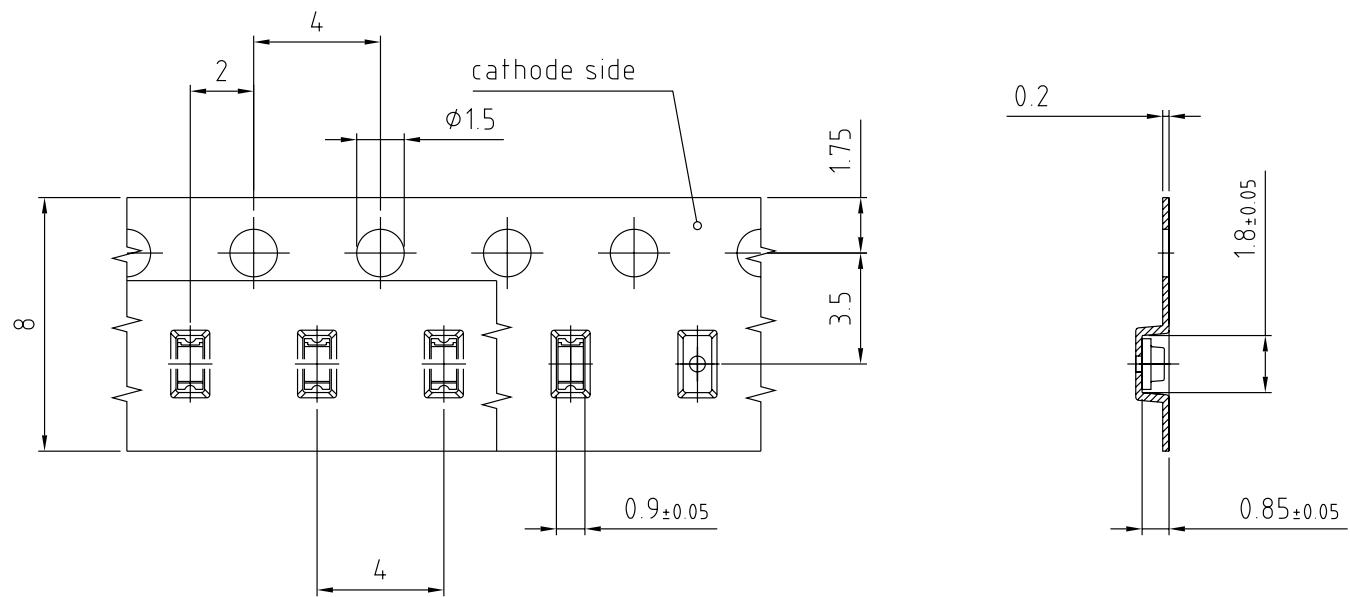


Profile Feature	Symbol	Pb-Free (SnAgCu) Assembly			Unit
		Minimum	Recommendation	Maximum	
Ramp-up rate to preheat*) $25\text{ }^{\circ}\text{C}$ to $150\text{ }^{\circ}\text{C}$			2	3	K/s
Time t_s $T_{S\min}$ to $T_{S\max}$	t_s	60	100	120	s
Ramp-up rate to peak*) $T_{S\max}$ to T_p			2	3	K/s
Liquidus temperature	T_L	217			$^{\circ}\text{C}$
Time above liquidus temperature	t_L	80	100	100	s
Peak temperature	T_p	245	260	260	$^{\circ}\text{C}$
Time within $5\text{ }^{\circ}\text{C}$ of the specified peak temperature $T_p - 5\text{ K}$	t_p	10	20	30	s
Ramp-down rate*) T_p to $100\text{ }^{\circ}\text{C}$			3	6	K/s
Time $25\text{ }^{\circ}\text{C}$ to T_p			480	480	s

All temperatures refer to the center of the package, measured on the top of the component

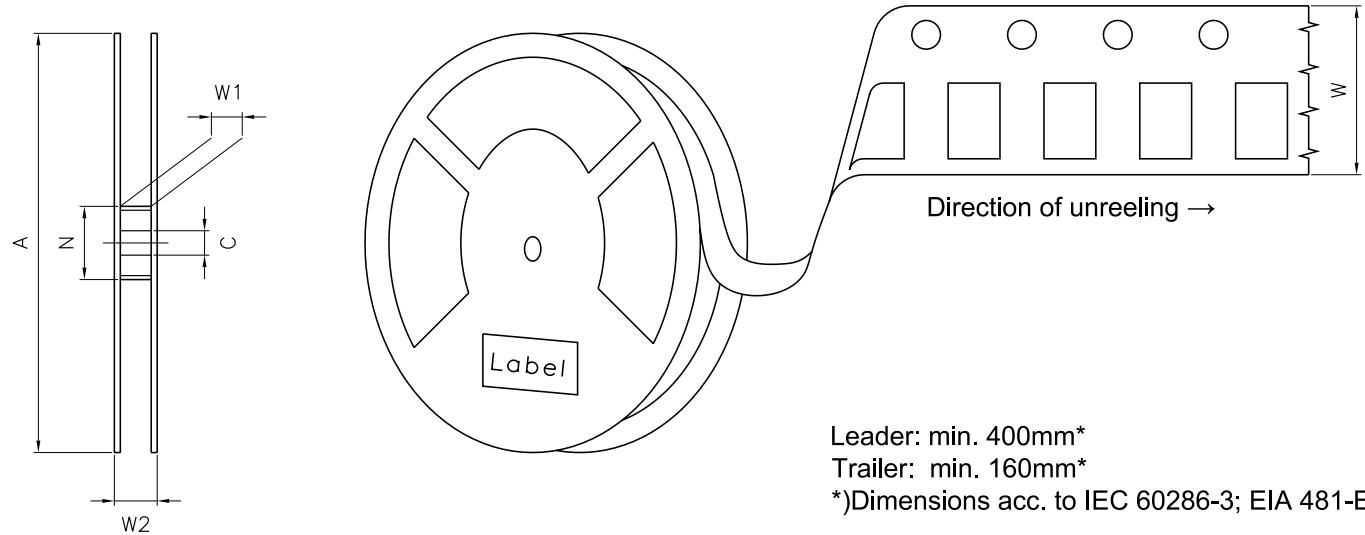
* slope calculation DT/Dt : Dt max. 5 s; fulfillment for the whole T -range

Taping ⁸⁾



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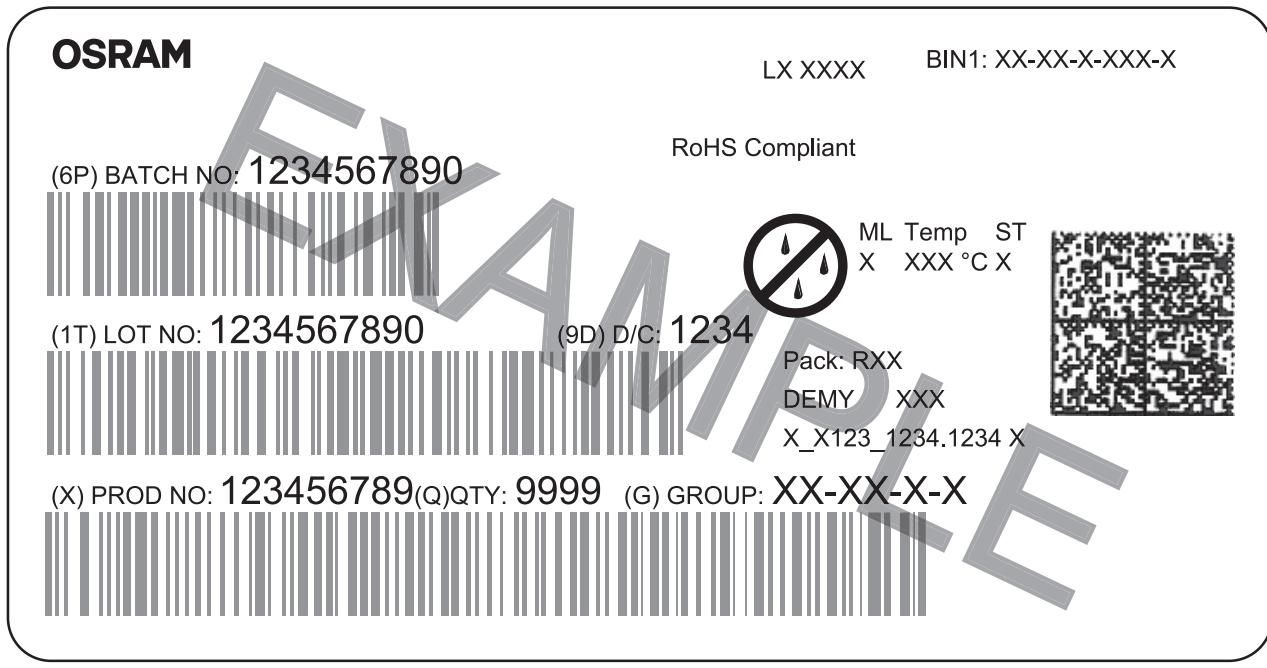
Tape and Reel ⁹⁾



Reel Dimensions

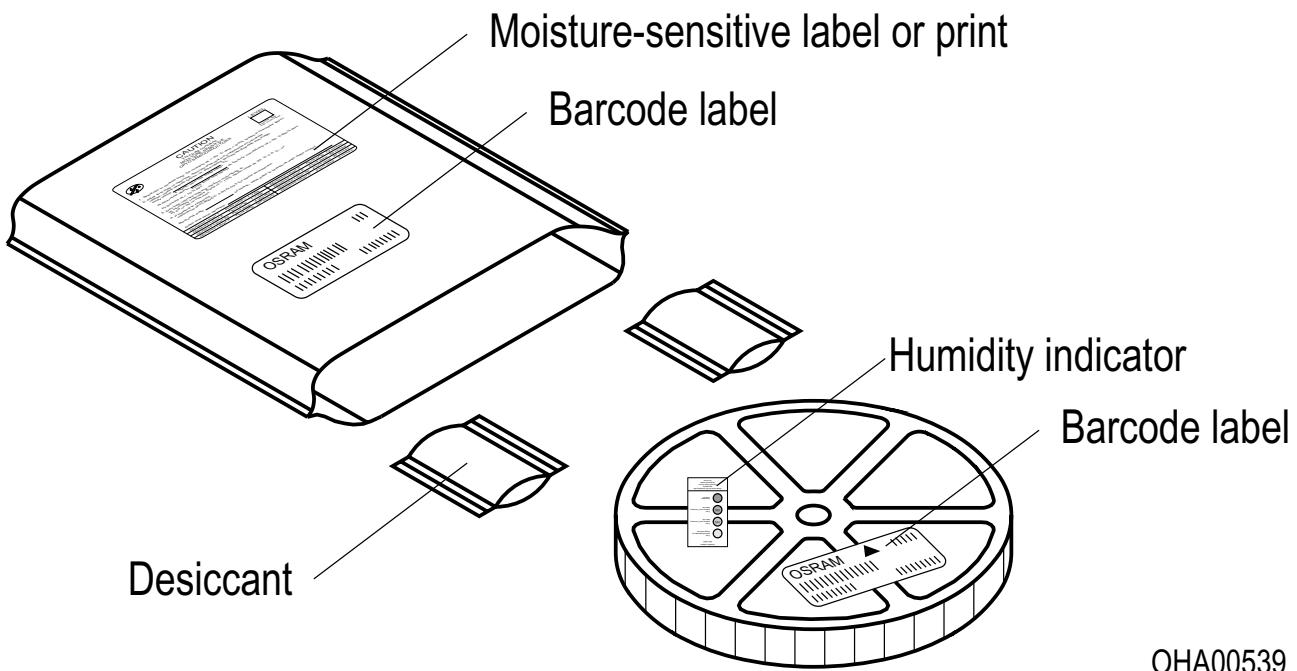
A	W	N_{\min}	W_1	$W_{2\max}$	Pieces per PU
180 mm	$8 + 0.3 / - 0.1$ mm	58 mm	$8.4 + 1,5$ mm	14.4 mm	4000

Barcode-Product-Label (BPL)



OHA04563

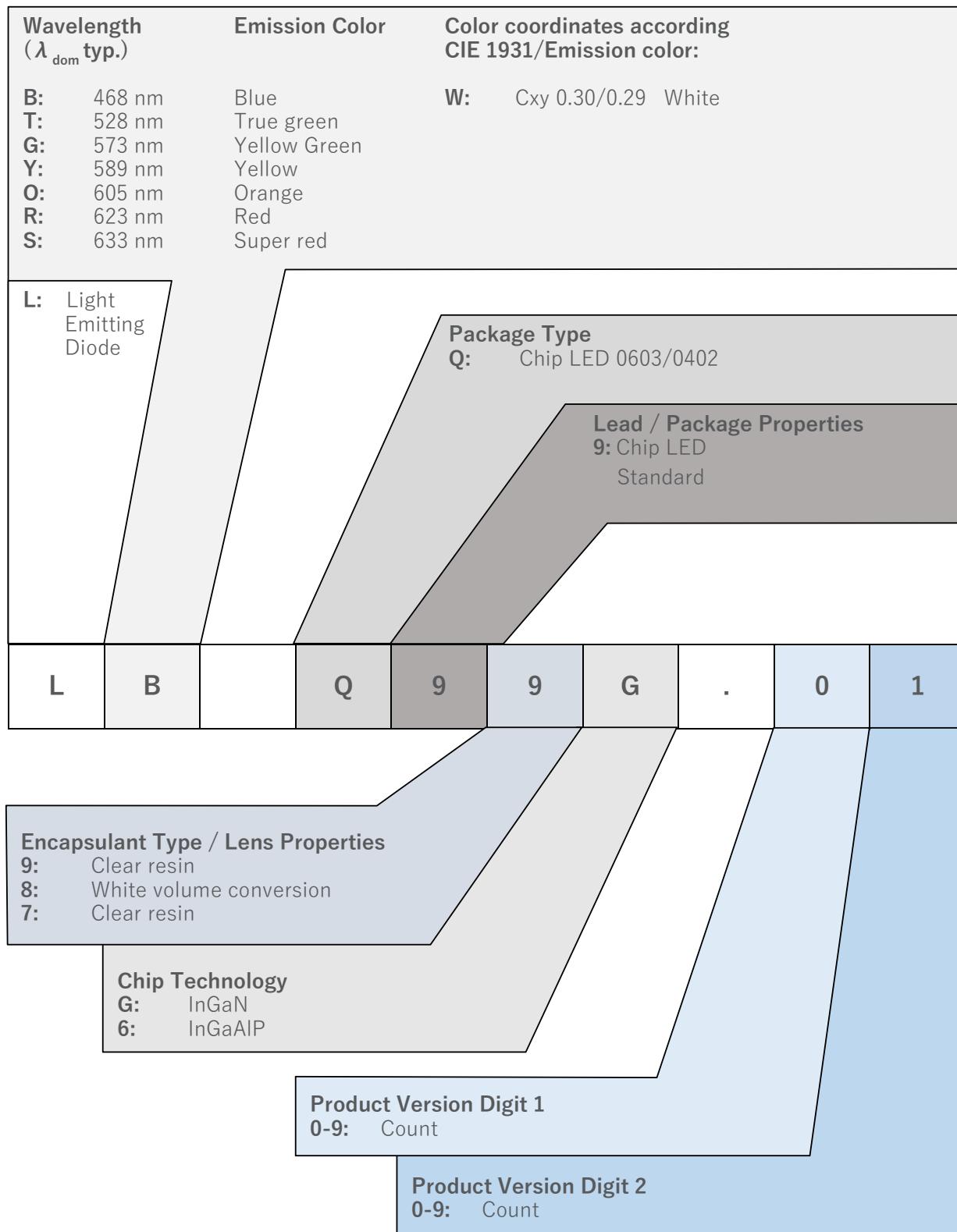
Dry Packing Process and Materials ⁸⁾



OHA00539

Moisture-sensitive product is packed in a dry bag containing desiccant and a humidity card according JEDEC-STD-033.

Type Designation System



Notes

The evaluation of eye safety occurs according to the standard IEC 62471:2006 (photo biological safety of lamps and lamp systems). Within the risk grouping system of this IEC standard, the device specified in this data sheet fall into the class **low risk (exposure time 100 s)**. Under real circumstances (for exposure time, conditions of the eye pupils, observation distance), it is assumed that no endangerment to the eye exists from these devices. As a matter of principle, however, it should be mentioned that intense light sources have a high secondary exposure potential due to their blinding effect. When looking at bright light sources (e.g. headlights), temporary reduction in visual acuity and afterimages can occur, leading to irritation, annoyance, visual impairment, and even accidents, depending on the situation.

Subcomponents of this device contain, in addition to other substances, metal filled materials including silver. Metal filled materials can be affected by environments that contain traces of aggressive substances. Therefore, we recommend that customers minimize device exposure to aggressive substances during storage, production, and use. Devices that showed visible discoloration when tested using the described tests above did show no performance deviations within failure limits during the stated test duration. Respective failure limits are described in the IEC60810.

For further application related information please visit <https://ams-osram.com/support/application-notes>

Disclaimer

Attention please!

The information describes the type of component and shall not be considered as assured characteristics. Terms of delivery and rights to change design reserved. Due to technical requirements components may contain dangerous substances.

For information on the types in question please contact our Sales Organization.
If printed or downloaded, please find the latest version on our website.

Packing

Please use the recycling operators known to you. We can also help you – get in touch with your nearest sales office. By agreement we will take packing material back, if it is sorted. You must bear the costs of transport. For packing material that is returned to us unsorted or which we are not obliged to accept, we shall have to invoice you for any costs incurred.

Product and functional safety devices/applications or medical devices/applications

Our components are not developed, constructed or tested for the application as safety relevant component or for the application in medical devices.

Our products are not qualified at module and system level for such application.

In case buyer – or customer supplied by buyer – considers using our components in product safety devices/applications or medical devices/applications, buyer and/or customer has to inform our local sales partner immediately and we and buyer and /or customer will analyze and coordinate the customer-specific request between us and buyer and/or customer.

Glossary

- 1) **Brightness:** Brightness groups are tested at a current pulse duration of 25 ms and a tolerance of $\pm 11\%$.
- 2) **Reverse Operation:** This product is intended to be operated applying a forward current within the specified range. Applying any continuous reverse bias or forward bias below the voltage range of light emission shall be avoided because it may cause migration which can change the electro-optical characteristics or damage the LED.
- 3) **Wavelength:** Wavelengths are tested at a current pulse duration of 25 ms and a tolerance of $\pm 1\text{ nm}$.
- 4) **Forward Voltage:** Forward voltages are tested at a current pulse duration of 1 ms and a tolerance of $\pm 0.1\text{ V}$.
- 5) **Thermal Resistance:** $R_{th\ max}$ is based on statistic values (6σ) used for Derating.
- 6) **Typical Values:** Due to the special conditions of the manufacturing processes of semiconductor devices, the typical data or calculated correlations of technical parameters can only reflect statistical figures. These do not necessarily correspond to the actual parameters of each single product, which could differ from the typical data and calculated correlations or the typical characteristic line. If requested, e.g. because of technical improvements, these typ. data will be changed without any further notice.
- 7) **Characteristic curve:** In the range where the line of the graph is broken, you must expect higher differences between single devices within one packing unit.
- 8) **Tolerance of Measure:** Unless otherwise noted in drawing, tolerances are specified with ± 0.1 and dimensions are specified in mm.
- 9) **Tape and Reel:** All dimensions and tolerances are specified acc. IEC 60286-3 and specified in mm.

Revision History

Version	Date	Change
1.0	2023-02-09	Initial Version
1.1	2024-06-19	Notes
1.2	2024-09-05	Description
1.3	2025-07-29	Recommended Solder Pad



EU RoHS and China RoHS compliant product

此产品符合欧盟 RoHS 指令的要求；

按照中国的相关法规和标准，

不含有毒有害物质或元素。

Published by ams-OSRAM AG

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